

Listing of the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

1-72. (Cancelled)

73. (Previously Presented) An in-process device, comprising:

a substrate;

a conductive layer over said substrate and having a surface stuffed with a non-oxygen material; and

a second conductive layer formed on the conductive layer and a third conductive layer formed on the second conductive layer, wherein the conductive layer comprises a metal layer, the second conductive layer comprises a tungsten nitride layer, and the third conductive layer comprises copper.

74. (Original) The in-process device of claim 73, wherein said surface is a nitrogen-stuffed surface.

75. (Cancelled)

76. (Previously Presented) The in-process device of claim 73 wherein the conductive layer has been exposed to a material selected from the group consisting of methylsilane, hexamethyldisilane and hexamethyldisilazane.

77-79. (Cancelled)

80. (Previously Presented) The in-process device of claim 73 wherein the substrate comprises a silicon substrate.

81. (Previously Presented) An in-process device, comprising:
a substrate;

a passivated conductive layer over the substrate, the passivated conductive layer having a reduced ability to associate with oxygen by being exposed to a material selected from the group consisting of phosphine and methylsilane; and

a second conductive layer formed on the conductive layer and a third conductive layer formed on the second conductive layer, wherein the conductive layer comprises a metal layer, the second conductive layer comprises a tungsten nitride layer, and the third conductive layer comprises copper.

82. (Previously Presented) The in-process device of claim 81 wherein the conductive layer comprises tungsten nitride.

83. (Previously Presented) The in-process device of claim 82 further comprising another conductive layer formed on the tungsten nitride layer.

84. (Previously Presented) The in-process device of claim 83 wherein the another conductive layer comprises copper.

85-86 (Cancelled)

87. (Previously Presented) The in-process device of claim 81 wherein the substrate comprises a silicon substrate.

88. (Previously Presented) An in-process device, comprising:
a substrate; and

a passivated conductive layer over the substrate, the passivated conductive layer having a reduced ability to associate with oxygen by being exposed to methylsilane.

89. (Previously Presented) The in-process device of claim 88 wherein the conductive layer comprises tungsten nitride.

90. (Previously Presented) The in-process device of claim 89 further comprising another conductive layer formed on the tungsten nitride layer.

91. (Previously Presented) The in-process device of claim 90 wherein the another conductive layer comprises copper.

92. (Previously Presented) The in-process device of claim 88 further comprising a second conductive layer formed on the conductive layer and a third conductive layer formed on the second conductive layer.

93. (Previously Presented) The in-process device of claim 92 wherein the conductive layer comprises a metal layer, the second conductive layer comprises a tungsten nitride layer, and the third conductive layer comprises copper.

94. (Previously Presented) The in-process device of claim 88 wherein the substrate comprises a silicon substrate.

95-99. (Cancelled)